

Amendments to the Specification:

On page 12, amend the first full paragraph as follows:

To protect the semiconductor chips 4, the cavity 3 is filled entirely with a radiation-pervious, for example transparent, encapsulation compound 6 which envelops the semiconductor chip 4 and which is pervious to radiation for emission or reception by the semiconductor chips 4.

As in the conventional components, suitable filling compounds made of transparent artificial resins, such as epoxy resin, or made of polycarbonate may be used for this encapsulation compound 6, which is preferably particularly in tune with the properties of the filling compound.

A cap 5 covers the encapsulation compound 6 and the front of the basic housing 20.